506652900 05/10/2021

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6699711

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
WEIWEI GE	05/08/2021

RECEIVING PARTY DATA

Name:	JOULWATT TECHNOLOGY CO., LTD.
Street Address:	ROOM 901-23, 9TH FLOOR, BUILDING 4, WEST PORT DEVELOPMENT CENTER
Internal Address:	NO. 298 ZHEN HUA ROAD, SANDUN TOWN XIHU DISTRICT,
City:	HANGZHOU
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	17315353	

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 408-384-9450

Email: cye@treasure-ip.com
Correspondent Name: TREASURE IP GROUP
Address Line 1: 106 OAKLAND PL

Address Line 4: LOS GATOS, CALIFORNIA 95032

ATTORNEY DOCKET NUMBER:	21212CC
NAME OF SUBMITTER:	QING YE
SIGNATURE:	/Qing Ye/
DATE SIGNED:	05/10/2021

Total Attachments: 3

source=21212CC-exeAssignment#page1.tif source=21212CC-exeAssignment#page2.tif source=21212CC-exeAssignment#page3.tif

PATENT 506652900 REEL: 056179 FRAME: 0985

Docket No. 21212CC "Assignment Signature Page" SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF ASSIGNMENT

WHEREAS I/We, the below named inventor(s),

Weiwei GE of Hangzhou, China

hereby sell and assign to Joulwatt Technology Co., Ltd., whose post office address is Room Room 901-23, 9th Floor, Building 4, West Port Development Center, NO. 298 ZHEN HUA Road, Sandun Town Xihu District, Hangzhou Zhejiang Province 310030, China, hereinafter referred to as "Company", its successors and assigns our entire respective rights, titles and interests in and to the invention and improvements invented and originated by us and for United States Patent currently entitled:

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

Executed concurrently herewith,

and any and all applications for patent and patents therefrom in any and all countries, including all divisions, continuations, reexaminations and reissues thereof, and all rights of priority resulting from the filing of said United States application, and authorize and request any official whose duty it is to issue patents, to issue any patent on said inventions and improvements resulting therefrom to said Company, or its successors or assigns and agree that on request and without further consideration, but at the expense of said Company, we will communicate to said Company or its representatives or nominees any facts known to us respecting said inventions and improvements and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, reexamination and reissue applications, make all rightful oaths and generally do everything possible to aid said Company, its successors, assigns, and nominees to obtain and enforce proper patent protection for said invention and its improvements in all countries.

Page 1 of 3

Docket No. 21212CC "Assignment Signature Page" SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

AND We/I hereby authorize and request our/my agents, USPTO customer number 93229, whose address is 106 Oakland PI, Los Gatos, CA 95032, to insert hereon any identification necessary or desirable for recordation of this document, including the filing date and application number of said application when known.

AND We/I hereby covenant for ourselves/myself and our/my legal representatives, and agree with said Company, its successors and assigns, that We/I have granted no right or license to make, use, sell or offer to sell said improvements, to anyone except said Company, that prior to the execution of this assignment document, our/my right, title and interest in said improvements had not been otherwise encumbered, and that We/I have not and will not execute any instrument in conflict therewith;

AND We/I do hereby authorize and request the Director of the United States Patent and Trademark Office to issue any and all letters patent which may be granted upon said United States applications, or upon said improvements or any parts thereof when granted, to said Company.

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF				
INVENTOR 1 Signature: Weiwei GE	Date:	05/08/2021		
Witnessed by: Xinyan Wang		05/08/2021		
Vinena Wana	of Witness	<u> </u>		
Witnessed by: Fei	Date:	05/08/2021		
Fei Ye				
Printed Nami	e of Witness			